

26.06.2018

1. Revision History

| VERSION | DATE | REVISED PAGE NO. | Note |
|---------|------------|------------------|---------------|
| 0 | 26.06.2018 | | First Release |

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1. General Specification

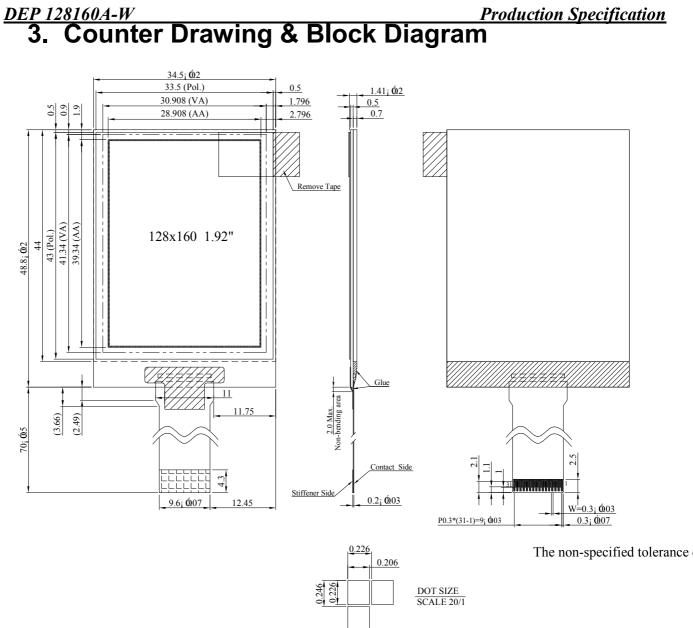
The Features is described as follow:

- Module Dimension: 34.50 x 48.80 x 1.41 mm
- Active Area: 28.908 x 39.34 mm
- Dot Matrix: 128 x 160
- Pixel Size: 0.206 x 0.226 mm
- Pixel Pitch: 0.226 x 0.246 mm
- Display Mode: Passive Matrix
- Duty: 1/128 Duty
- Display Color: White
- IC: SH1108
- Interface: 6800,8080, SPI, I2C
- Size: 1.92 Inch

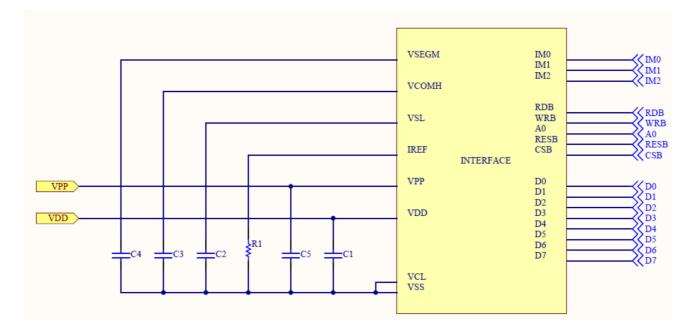
2. Interface Pin Function

| No. | Symbol | Function | | | | | |
|-----|--------|--|--|--------------|--------------|---------------|-----------------------|
| 1 | NC | NC | | | | | |
| 2 | VPP | It should be | This is the most positive voltage supply pad of the chip. It should be supplied externally. | | | | |
| 3 | VSEGM | This is a pa A capacitor | | | | | pre-charge. d VSS. |
| 4 | VCOMH | This is a pa signals. A capacitor | | • | U U | | |
| 5 | VSL | This is a se A capacitor | | | | his pad an | d VSS. |
| 6 | NC | NC | NC | | | | |
| 7 | IREF | This is a segment current reference pad. A resistor should be connected between this pad and VSS. Set the current at 15.625uA. | | | | | |
| 8 | VPP | This is the most positive voltage supply pad of the chip. It should be supplied externally. | | | | | |
| 9 | NC | NC | | | | | |
| 10 | VSS | Ground for | analog, lo | gic &buffer | respective | ly. | |
| 11 | VCL | This is a co This pad sl | | | | rnally. | |
| 12 | VDD | 1.65 - 3.5∨ | power sup | oply input p | ad for logic | C. | |
| 13 | IMO | These are | the MPU ir | nterface mo | ode select i | | 0.14/ |
| 14 | IM1 | | 8080 | I2C | 6800 | 4-Wire SPI | 3-Wire SPI |
| | | IM0 | 0 | 0 | 0 | 0 | 1 |
| 16 | IM2 | IM1 | 1 | 1 | 0 | 0 | 0 |
| | | IM2 | 1 | 0 | 1 | 0 | 0 |
| 15 | VDD | 1.65 - 3.5∨ | • | | | | |
| 17 | CS | This pad is select beco | • | • | | | • |

| DEP 1281 | 160A-W | Production Specification |
|-----------------|--------|---|
| 18 | RES | This is a reset signal input pad. When /RES is set to "L", the settings are initialized. The reset operation is performed by the /RES signal level. |
| 19 | A0 | This is the Data/Command control pad that determines whether the data bits are data or a command. A0 = "H": the inputs at D0 to D7 are treated as display data. A0 = "L": the inputs at D0 to D7 are transferred to the command registers. In I2C interface, this pad serves as SA0 to distinguish the different address of OLED driver. |
| 20 | WR | This is a MPU interface input pad. When connected to an 8080 MPU, this is active LOW. This pad connects to the 8080 MPU /WR signal. The signals on the data bus are latched at the rising edge of the /WR signal .When connected to a 6800 Series MPU: This is the read/write control signal input terminal .When /WR = "H": Read .When /WR = "L": Write. |
| 21 | RD | This is a MPU interface input pad. When connected to an 8080 series MPU, it is active LOW. This pad is connected to the /RD signal of the 8080 series MPU, and the data bus is in an output status when this signal is "L". When connected to a 6800 series MPU, this is active HIGH. This is used as an enable clock input of the 6800 series MPU. |
| 22 | D0 | Data bus. |
| 23 | D1 | Data bus. |
| 24 | D2 | Data bus. |
| 25 | D3 | Data bus. |
| 26 | D4 | Data bus. |
| 27 | D5 | Data bus. |
| 28 | D6 | Data bus. |
| 29 | D7 | Data bus. |
| 30 | NC | NC |
| 31 | VPP | This is the most positive voltage supply pad of the chip. It should be supplied externally. |



3.1 Application Recommendations



Recommended Components : C1: 0.1uF C2,C3,C4,C5: 4.7µF R1: about 750kOhm , R1 = (Voltage at IREF – GND)/IREF

Bus Interface selection: (Must be set the IM[2:0], refer to item 4) 8-Bits 6800 and 8080 parallel, 3 or 4-Wire SPI, I2C

*For more information, please contact us.

4. Absolute Maximum Ratings

| Parameter | Symbol | Min | Мах | Unit |
|----------------------------|--------|------|------|------|
| Supply Voltage for Logic | VDD | -0.3 | 3.6 | V |
| Supply Voltage for Display | VPP | -0.3 | 17.0 | V |
| Operating Temperature | TOP | -40 | +80 | °C |
| Storage Temperature | TSTG | -40 | +85 | °C |

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6. "Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

5. Electrical Characteristics

5.1 DC Electrical Characteristics

| ltem | Symbol | Condition | Min | Тур | Max | Unit |
|--|--------|------------|---------|------|---------|------|
| Supply Voltage for Logic | VDD | | 1.65 | 3.0 | 3.5 | V |
| Supply Voltage for Display | VPP | _ | 11.5 | 12.0 | 12.5 | V |
| Input High Volt. | VIH | _ | 0.8xVDD | _ | VDD | V |
| Input Low Volt. | VIL | _ | VSS | _ | 0.2xVDD | V |
| Output High Volt. | VOH | IOH=-0.5mA | 0.8xVDD | _ | VDD | V |
| Output Low Volt. | VOL | IOL=0.5mA | VSS | _ | 0.2xVDD | V |
| Operating Current for VPP (VCC Supplied Externally) | Ірр | VPP=12.0V | _ | 23.0 | 34.5 | mA |

<u>DEP 128160A-W</u> 5.2 Initial Code Proposal

WriteCommand(0xAE); // Display OFF

WriteCommand(0x20); // Set Memory addressing mode

WriteCommand(0x81); // Set contrast control

WriteCommand(0x78);

WriteCommand(0xA0); // Segment remap

WriteCommand(0xA6); // Normal display

WriteCommand(0xA9); // Set Display Resolution

WriteCommand(0x02); // 160*128

WriteCommand(0xAD); // Set external VPP

WriteCommand(0x80);

WriteCommand(0xC0); // Set Common scan direction

WriteCommand(0xD5); // Divide Ratio/Oscillator Frequency Mode Set

WriteCommand(0xF1); // 86Hz

WriteCommand(0xD9); // Set Dis-charge/Pre-charge Period

WriteCommand(0x1F); // 0.687*VPP

WriteCommand(0xDB); // Set Vcomh voltage

WriteCommand(0x2B);

WriteCommand(0xDC); // Set VSEGM Deselect Level

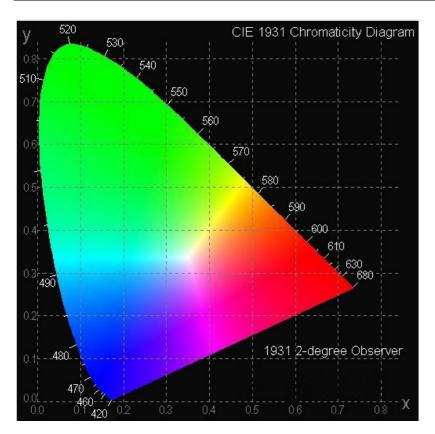
WriteCommand(0x35);

WriteCommand(0x30); // Set Discharge VSL Level,0V

WriteCommand(0xAF); // Display ON

6. Optical Characteristics

| ltem | Symbol | Condition | Min | Тур | Max | Unit |
|------------------|-----------|-----------|--------|------|-------|------|
| | (V)θ | _ | 160 | _ | _ | deg |
| View Angle | (H)φ | _ | 160 | _ | _ | deg |
| Contrast Ratio | CR | Dark | 2000:1 | _ | _ | |
| December 75 | T rise | _ | _ | 10 | _ | μs |
| Response Time | T fall | _ | _ | 10 | _ | μs |
| Display with 50% | htness | 60 | 80 | _ | cd/m2 | |
| CIEx(White) | (CIE1931) | 0.24 | 0.28 | 0.32 | | |
| CIEy(White) | | (CIE1931) | 0.28 | 0.32 | 0.36 | |



DEP 128160A-W 7. OLED Lifetime

| ITEM | Conditions | Min | Тур | Remark |
|-----------------------|--|------------|-----|--------|
| Operating Lifetime | Ta=25°C / Initial 50% check board brightness Typical Value | 16.000 Hrs | - | Note |

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.

8. Reliability

Content of Reliability Test

| Environmenta | l Test | | |
|---|---|---|------------------------|
| Test Item | Content of Test | Test Condition | Applicable Standard |
| High Temperature storage | Endurance test applying the high storage temperature for a long time. | +85°C 240hrs | |
| Low Temperature storage | Endurance test applying the low storage temperature for a long time. | -40°C 240hrs | |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | +80°C 240hrs | |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -40°C 240hrs | |
| High Temperature/ Humidity Storage | Endurance test applying the high temperature and high humidity storage for a long time. | +60°C,90%RH 240hrs | |
| High Temperature/ Humidity Operation | Endurance test applying the high temperature and high humidity Operation for a long time. | +60°C,90%RH 120hrs | |
| Temperature Cycle | Endurance test applying the low and high temperature cycle. -40°C +25°C +80°C 30min 5min 30min 1 cycle | -40°C /+80°C 30 cycles | |
| Mechanical Tes | st | | |
| Vibration test | Endurance test applying the vibration during transportation and using. | Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z | |
| Others | | | |
| Static electricity test | Endurance test applying the electric stress to the terminal. | Air Discharge Model ±4kV,10 times | |

*** Supply voltage for OLED system =Operating voltage at 25°C

<u>DEP 128160A-W</u>

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23°C ± 5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

9. Inspection specification

Inspection Standard:

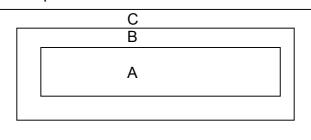
MIL-STD-105E table normal inspection single sample level II.

Definition

1 Major defect: The defect that greatly affect the usability of product.

2 Minor defect: The other defects, such as cosmetic defects, etc.

Definition of inspection zone:



Zone A: Active Area

Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer's product.

Inspection Methods

- 1 The general inspection: Under fluorescent light illumination: 750~1500 Lux, about 30cm viewing distance, within 45° viewing angle, under 25°C ± 5°C.
- 2 The luminance and color coordinate inspection : By SR-3 or BM-7 or the equal equipments in the dark room, under $25^{\circ}C \pm 5^{\circ}C$.

| NO | Item | Criterion | AQL |
|----|--|--|------|
| 01 | Electrical Testing | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. | 0.65 |
| 02 | Black or white spots on OLED (display only) | 2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. | 2.5 |

| <u>DEP</u> | <u>Р 128160А-И</u> | V | | Produ | ction Spec | <u>cification</u> |
|------------|--|---|--|---|---------------------------------------|-------------------|
| NO | Item | | Criterion | I | | AQL |
| | OLED black spots, white spots, contamin ation (non-display) | 3.1 Round type : As following drawing $\Phi=(x + y) / 2$ | $SIZE \\ \Phi \le 0.10 \\ 0.10 < \Phi \le 0.20 \\ 0.20 < \Phi \le 0.25 \\ 0.25 < \Phi$ | Acceptable QTY Accept no dense 2 1 0 | Zone A+ B, A+ B A+ B A+ B | 2.5 |
| 03 | | 3.2 Line type : (As | | Acceptable Q TY Accept no | Zone A+B | 2.5 |
| | | L≦3.0 L≦2.8 | | - 2 | A+B A+B | |
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. | Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY | Acceptable Q TY Accept no dense 3 2 0 3 3 | Zone A+B A+B A+B A+B | 2.5 |
| 05 | Scratches | Follow NO.3 OLED | black spots, white | spots, contamination | on. | |

DEP 128160A-W Production Specification

| NO | Item | Criterion | AQL |
|----|------------------|--|-----|
| | | Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: x y x | 2.5 |
| | Chipped glass | $\begin{tabular}{ c c c c c } \hline Z \leq 1/2t & \mbox{Not over viewing area} & x \leq 1/8a \\ \hline 1/2t < z \leq 2t & \mbox{Not exceed } 1/3k & x \leq 1/8a \\ \hline \odot \mbox{ If there are 2 or more chips, x is total length of each chip.} \end{tabular}$ | |
| 06 | | 6.1.2 Corner crack: \overrightarrow{x} \overrightarrow{y} \overrightarrow{x} \overrightarrow{y} \overrightarrow{x} \overrightarrow{x} \overrightarrow{x} \overrightarrow{x} \overrightarrow{x} \overrightarrow{x} \overrightarrow{x} \overrightarrow{x} \overrightarrow{x} \cancel{x} <td>2.5</td> | 2.5 |
| | Glass crack | $\begin{array}{c c} \text{Symbols :} \\ \text{x: Chip length} & \text{y: Chip width} & \text{z: Chip thickness} \\ \text{k: Seal width} & \text{t: Glass thickness} & \text{a: OLED side length} \\ \text{L: Electrode pad length} \\ \text{6.2 Protrusion over terminal :} \\ \text{6.2.1 Chip on electrode pad :} \\ \hline \\ $ | 2.5 |

Production Specification

| NO | Item | Criterion | AQL |
|----|-----------------------|---|---------------------|
| 06 | Glass crack | 6.2.2 Non-conductive portion: y y x x y y x y | 2.5 |
| 07 | Cracked glass | The OLED with extensive crack is not acceptable. | 2.5 |
| 08 | Backlight elements | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. | 0.65 2.5 0.65 |
| 09 | Bezel | 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications. | 2.5 0.65 |

Production Specification

| | <u>DEP 128160A-W</u> Production Specif | | | | |
|----|--|---|--------------|--|--|
| NO | Item | Criterion | AQL | | |
| 10 | PCB , COB | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. | 2.5 | | |
| | | 10.2 COB seal surface may not have pinholes through to the IC. | 2.5 | | |
| | | 10.3 The height of the COB should not exceed the height | 0.65 | | |
| | | indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. | 2.5 | | |
| | | 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. | 2.5 0.65 | | |
| | | 10.7 The jumper on the PCB should conform to the product characteristic chart. | 0.65 | | |
| | | 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. | 2.5 | | |
| | Soldering | 11.1 No un-melted solder paste may be present on the PCB. | 2.5 | | |
| 11 | | 11.2 No cold solder joints, missing solder connections, oxidation or icicle. | 2.5 | | |
| | | 11.3 No residue or solder balls on PCB. | 2.5 | | |
| | | 11.4 No short circuits in components on PCB. | 0.65 | | |
| | General appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. | 2.5 | | |
| | | 12.2 No cracks on interface pin (OLB) of TCP. | 0.65 | | |
| 12 | | 12.3 No contamination, solder residue or solder balls on product. | 2.5 | | |
| | | 12.4 The IC on the TCP may not be damaged, circuits. | 2.5 | | |
| | | 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. | 2.5 | | |
| | | 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. | 2.5 | | |
| | | 12.7 Sealant on top of the ITO circuit has not hardened. | 2.5 | | |
| | | 12.8 Pin type must match type in specification sheet. | 0.65 | | |
| | | 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on | 0.65 0.65 | | |
| | | packaging specification sheet. | 0.00 | | |
| | | 12.11 Product dimension and structure must conform to product specification sheet. | 0.65 | | |

Production Specification

| 28160A-W | Production Spe | |
|--|----------------|--|
| Check Item | Classification | Criteria |
| No Display | Major | |
| Missing Line | Major | |
| Pixel Short | Major | |
| Darker Short | Major | |
| Wrong Display | Major | |
| Un-uniform B/A x 100% < 70% A/C x 100% < 70% | Major | A Normal B Dark Fixel IIIII IIIII IIIII IIIII IIIII IIIII IIII |

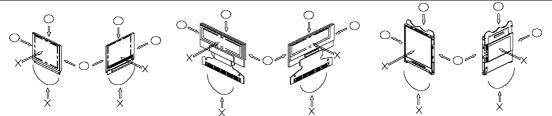
<u>DEP 128160A-W</u>

10. Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time that will extend "screen burn" effect time.
- (10) DISPLAY has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) DISPLAY have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, DISPLAY have the right to modify the version.)

10.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:
 * Water
 - * Ketone
 - * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



(7) Do not apply stress to the LSI chips and the surrounding molded sections.

(8) Do not disassemble nor modify the OLED display module.

(9) Do not apply input signals while the logic power is off.

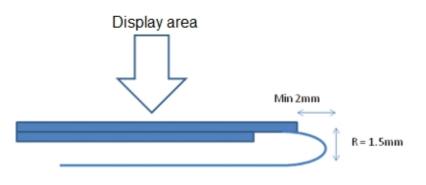
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.
 - * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
 - * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

10.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from DISPLAY. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

10.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.
- (8) The limitation of FPC and Film bending.



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